

U.S.S.N. 10,811,621

Claim Amendments

Please amend claims 1, 9, 17, and 21-26 as follows:

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Listing of Claims

1. (currently amended) An electrolyte bath, comprising:

an electrolyte solution suitable for metal electroplating; and

a composition comprising an organic acid and a non-ionic polymer mixed with said organic acid, said non-ionic polymer selected from the group consisting of an alkoxyated alcohol, an alkoxyated amine, and an alkylphenol alkoxyate;

wherein said composition is disposed as a suspended ~~suspension~~ layer within said electrolyte solution, said suspended ~~suspension~~ layer of sufficient dimension to form a wetting layer on a substrate as said substrate is passed through said suspended layer.

2. (previously presented) The electrolyte bath of claim 1 wherein said organic acid is selected from the group consisting of citric acid and acetic acid.

3. (canceled)

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4. (previously presented) The electrolyte bath of claim 1 wherein said composition is present in said electrolyte solution in a concentration of about 5 % by weight.

5. (previously presented) The electrolyte bath of claim 1 wherein said non-ionic polymer has a molecular weight of less than 1,000.

6. (previously presented) The electrolyte bath of claim 5 wherein said organic acid is selected from the group consisting of citric acid and acetic acid.

7. (previously presented) The electrolyte bath of claim 1 wherein said organic acid is present in said composition in a wt.% of about 10, and wherein said non-ionic polymer is present in said composition in a wt.% of about 5.

8. (canceled)

9. (currently amended) An electrolyte bath, comprising:

an electrolyte solution suitable for copper electroplating; and

a composition comprising an organic acid and a non-

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ionic polymer mixed with said organic acid, said non-ionic polymer selected from the group consisting of an alkoxyated alcohol, alkoxyated amine, and an alkylphenol alkoxyate, said organic acid selected from the group consisting of citric acid and acetic acid;

wherein said composition is disposed as a suspended ~~suspension~~ layer within said electrolyte solution, said suspended ~~suspension~~ layer of sufficient dimension to form a wetting layer on a substrate as said substrate is passed through said suspended ~~suspension~~ layer.

Claims 10-11 (canceled)

12. (previously presented) The electrolyte bath of claim 9 wherein said composition is present in said electrolyte solution in a concentration of about 5% by weight.

13. (previously presented) The electrolyte bath of claim 9 wherein said organic acid is present in said composition in a wt.% of about 10, and wherein said non-ionic polymer is present in said composition in a wt.% of about 5.

14. (canceled)

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Claims 15-16 (canceled)

17. (currently amended) A method for electroplating a metal onto a surface in an electroplating electrolyte solution, comprising the steps of:

providing a composition mixture comprising an organic acid and a non-ionic polymer;

forming a suspended ~~suspension~~ layer of said composition mixture within said electrolyte solution;

forming a wetting layer on said surface by passing said surface through said suspended ~~suspension~~ layer and into said electrolyte solution; and

electroplating said metal onto said surface following forming said wetting layer.

18. (previously presented) The method of claim 17 wherein said organic acid is selected from the group consisting of citric acid and acetic acid and said non-ionic polymer is selected from the group consisting of an alkoxylated alcohol, an alkoxylated amine, and an alkylphenol alkoxylate.

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19. (previously presented) The method of claim 18 wherein said organic acid is present in said composition in a wt.% of about 10, and wherein said non-ionic polymer is present in said composition in a wt.% of about 5.

20. (original) The method of claim 17 further comprising a substrate and wherein said surface comprises a metal seed layer deposited on said substrate.

21. (currently amended) The electrolyte bath of claim 1, wherein said non-ionic polymer is present in said composition ~~suspension layer~~ in a quantity of from about 0.5 to about 10 wt. %.

22. (currently amended) The electrolyte bath of claim 1, wherein said organic acid is present in said composition ~~suspension layer~~ in a quantity of from about 2 to about 20 wt. %.

23. (currently amended) The electrolyte bath of claim 9, wherein said non-ionic polymer is present in said composition ~~suspension layer~~ in a quantity of from about 0.5 to about 10 wt. %.

24. (currently amended) The electrolyte bath of claim 9, wherein said organic acid is present in said composition ~~suspension layer~~

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in a quantity of from about 2 to about 20 wt. %.

25. (currently amended) The method of claim 17, wherein said non-ionic polymer is present in said ~~suspension layer~~ composition mixture in a quantity of from about 0.5 to about 10 wt. %.

26. (currently amended) The method of claim 17, wherein said organic acid is present in said ~~suspension layer~~ composition mixture in a quantity of from about 2 to about 20 wt. %.